



Material Content Data Sheet



Sales Product Name		TDA21240		Issued		19. July 2018		
MA#		MA001581010						
Package		PG-IQFN-30-2		Weight*		56.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.202	2.15	2.15	21455	21455
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		82	
	non noble metal	zinc	7440-66-6	0.018	0.03		329	
	non noble metal	iron	7439-89-6	0.368	0.66		6576	
wire	non noble metal	copper	7440-50-8	14.956	26.70	27.40	267007	273994
	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1510	1510
	encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		834
	plastics	epoxy resin	-	2.406	4.30		42952	
	inorganic material	silicondioxide	60676-86-0	20.906	37.32	41.70	373227	417013
leadfinish	non noble metal	tin	7440-31-5	0.593	1.06	1.06	10582	10582
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	717	717
glue	plastics	epoxy resin	-	0.079	0.14		1412	
	noble metal	silver	7440-22-4	0.237	0.42	0.56	4236	5648
solder	noble metal	silver	7440-22-4	0.029	0.05		512	
	non noble metal	tin	7440-31-5	0.057	0.10		1024	
	non noble metal	lead	7439-92-1	1.061	1.89	2.04	18935	20471
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	zinc	7440-66-6	0.003	0.01		55	
	non noble metal	iron	7439-89-6	0.062	0.11		1100	
	non noble metal	copper	7440-50-8	2.502	4.47	4.59	44666	45835
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.01		61	
	non noble metal	zinc	7440-66-6	0.014	0.02		243	
	non noble metal	iron	7439-89-6	0.273	0.49		4867	
	non noble metal	copper	7440-50-8	11.069	19.76	20.28	197604	202775
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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